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APPLICATION NO.	FILING DATE	FIRST NAM	MED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/997,972 TITLE OF INVENTION: M	11/29/2001 ETHOD FOR MANUFAC		agju Wu E OF SEMICONDUCTOR DEV	TI-33005 (032350.B372) ICE WITH POLYSILICON D	4900 EFINITION STRUCTURE	
APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE	
nonprovisional	NO	\$1330	\$300	\$1630	06/25/2004	
EXAM	INER	ART UNIT	CLASS-SUBCLASS	<b>]</b> .		
LATTIN, CHR  1. Change of correspondence		2812	438-316000	-		
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

**Applicant** 

Xiaoju Wu

Docket Number: TI-33005

Serial No.: 09/997,972

Art Unit: 2812

Filed:

11/29/01

Examiner: Christopher W. Lattin

For:

Method for Manufacturing and Structure of Semiconductor

Device with Polysilicon Definition Structure

## **CERTIFICATION OF FACSIMILE TRANSMISSION**

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Karen Viert

3-30-04 Date

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NAME OF INVENTOR(S):		RECEIPT DATE & SERIAL NO.:			
Xiaoju Wu		Serial No.: 09/997,972			
TITLE OF INVENTION: Method Structure of Semiconductor D Definition Structure	for Manufacturing and evice with Polysilicon	Filing Date: 11/29/01			
TI FILE NO.:	DEPOSIT ACCT. NO.:	<b>- </b>			
TI-33005	20-0668				
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